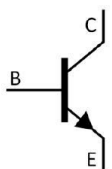


/ Descriptions

/ Features

/ Applications

/ Equivalent Circuit



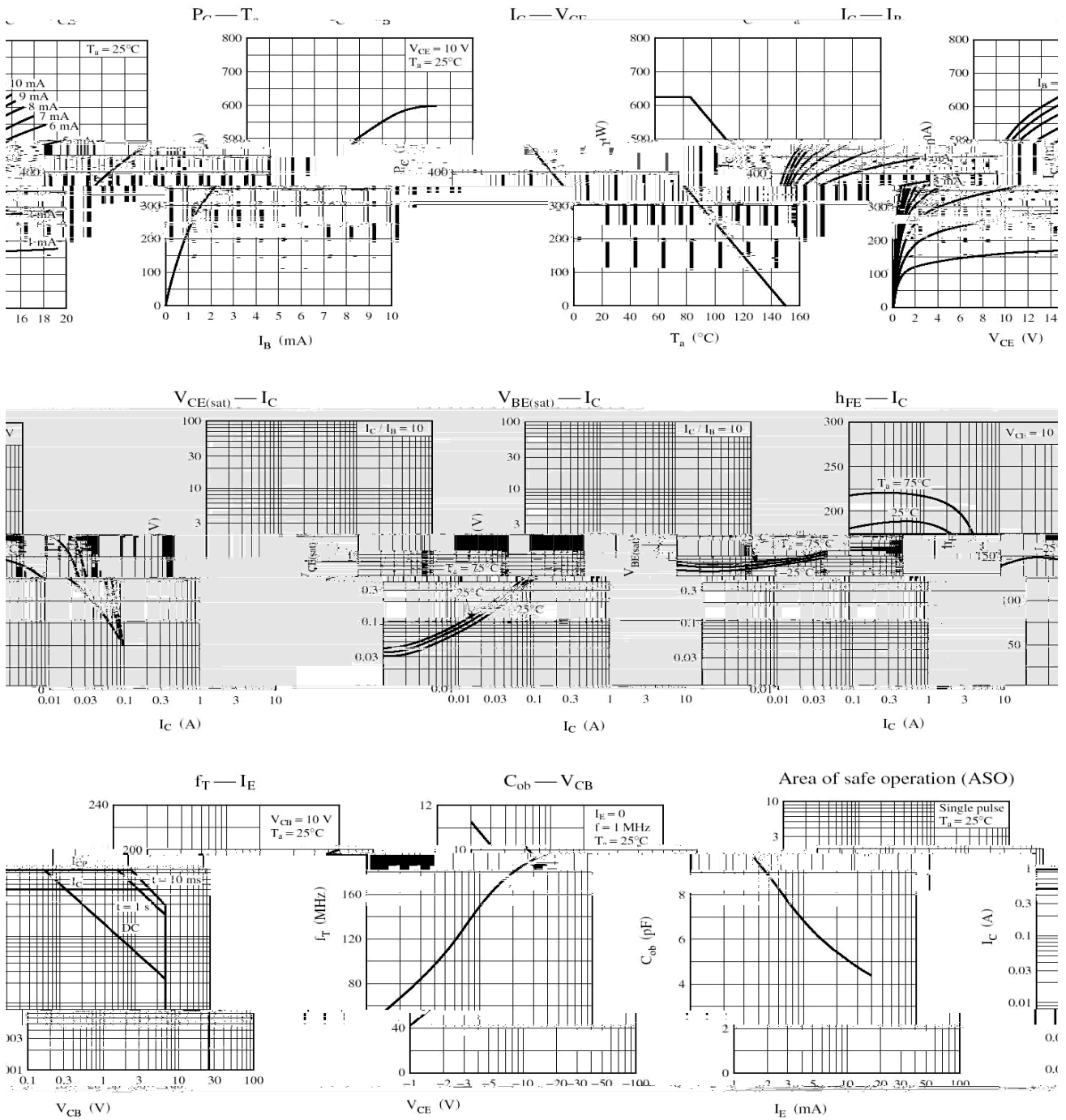
/ Pinning



/ hFE Classifications & Marking

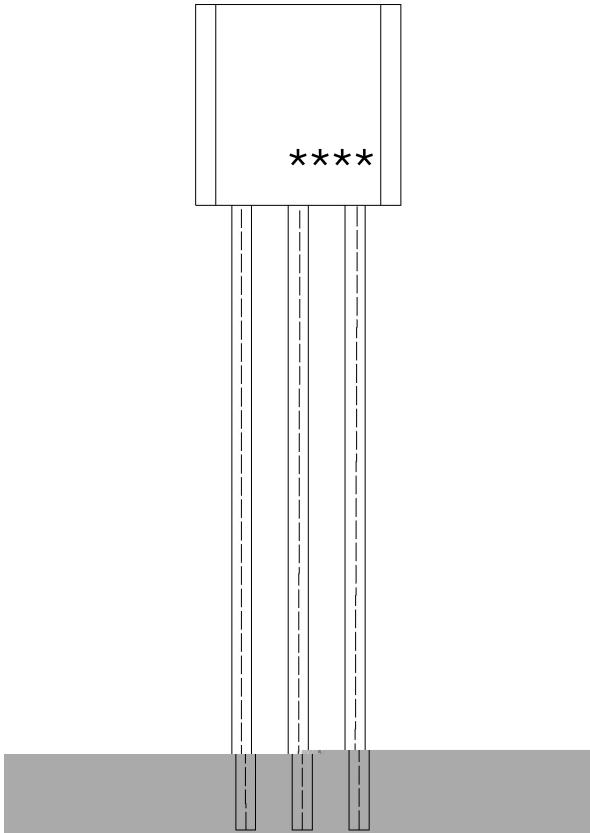
		μ				
		μ				

/ Electrical Characteristic Curve

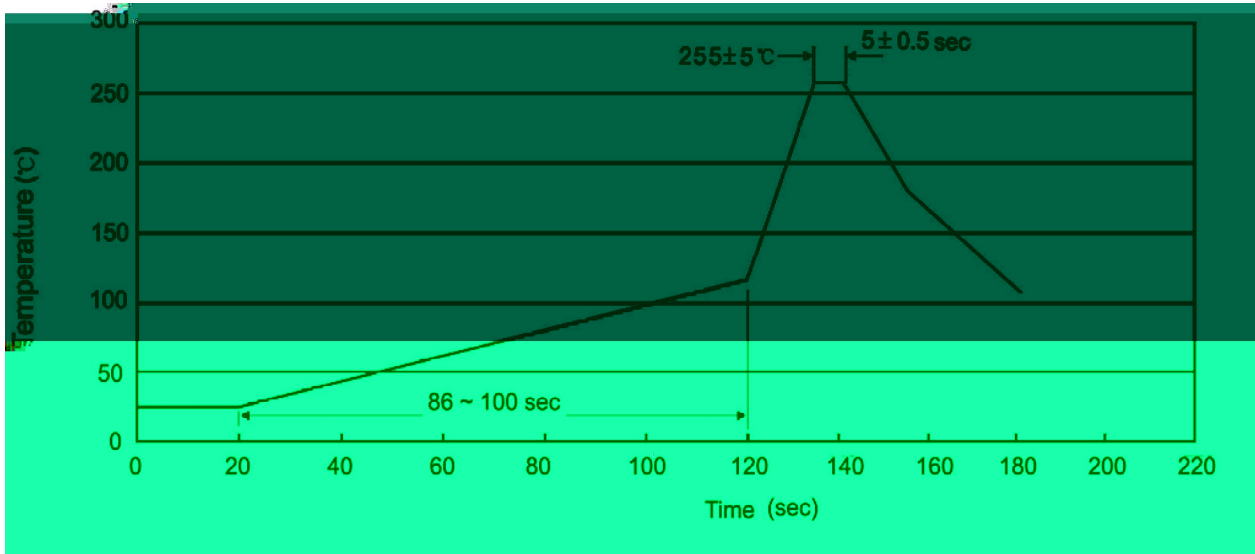


2SC1318

/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

封装形式	包装数量					包装尺寸 :	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92	3,000	1	120	10	30,000	328×230×42	小箱 480×346×235, 大箱 547×407×268